# 4-Bit Dual-Supply Inverting Level Translator

The NLSV4T240 is a 4-bit configurable dual-supply voltage level translator. The input  $A_n$  and output  $B_n$  ports are designed to track two different power supply rails,  $V_{\rm CCA}$  and  $V_{\rm CCB}$  respectively. Both supply rails are configurable from 0.9 V to 4.5 V allowing universal low-voltage translation from the input  $A_n$  to the output  $B_n$  port.

#### **Features**

- Wide V<sub>CCA</sub> and V<sub>CCB</sub> Operating Range: 0.9 V to 4.5 V
- High-Speed w/ Balanced Propagation Delay
- Inputs and Outputs have OVT Protection to 4.5 V
- Non-preferential V<sub>CCA</sub> and V<sub>CCB</sub> Sequencing
- Outputs at 3-State until Active V<sub>CC</sub> is Reached
- Power-Off Protection
- Outputs Switch to 3-State with V<sub>CCB</sub> at GND
- Ultra-Small Packaging: 1.7 mm x 2.0 mm UQFN12
- This is a Pb-Free Device

### **Typical Applications**

• Mobile Phones, PDAs, Other Portable Devices

### **Important Information**

• ESD Protection for All Pins: HBM (Human Body Model) > 6000 V

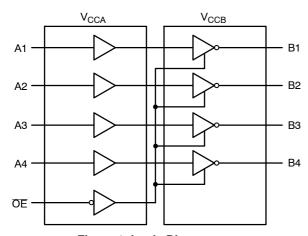


Figure 1. Logic Diagram



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### MARKING DIAGRAM

WBM=

UQFN12 MU SUFFIX CASE 523AE

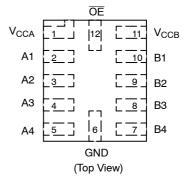
WB = Specific Device Code

M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

#### **PIN ASSIGNMENT**



### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NLSV4T240MUTAG	UQFN12 (Pb-Free)	

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

### **PIN ASSIGNMENT**

PIN	FUNCTION
V <sub>CCA</sub>	Input Port DC Power Supply
V <sub>CCB</sub>	Output Port DC Power Supply
GND	Ground
A <sub>n</sub>	Input Port
B <sub>n</sub>	Output Port
ŌĒ	Output Enable

### **TRUTH TABLE**

In	Inputs				
ŌĒ	A <sub>n</sub>	B <sub>n</sub>			
L	L	Н			
L	Н	L			
Н	Х	3-State			

### **MAXIMUM RATINGS**

Symbol	Rating		Value	Condition	Unit
V <sub>CCA</sub> , V <sub>CCB</sub>	DC Supply Voltage		−0.5 to +5.5		V
VI	DC Input Voltage	An	−0.5 to +5.5		V
V <sub>C</sub>	Control Input	ŌΕ	-0.5 to +5.5		V
Vo	DC Output Voltage (Power Down)	B <sub>n</sub>	-0.5 to +5.5	$V_{CCA} = V_{CCB} = 0$	V
	(Active Mode)	B <sub>n</sub>	-0.5 to +5.5		V
	(Tri-State Mode)	B <sub>n</sub>	-0.5 to +5.5		V
I <sub>IK</sub>	DC Input Diode Current		-20	V <sub>I</sub> < GND	mA
lok	DC Output Diode Current		-50	V <sub>O</sub> < GND	mA
I <sub>O</sub>	DC Output Source/Sink Current		±50		mA
I <sub>CCA</sub> , I <sub>CCB</sub>	DC Supply Current Per Supply Pin		±100		mA
I <sub>GND</sub>	DC Ground Current per Ground Pin		±100		mA
T <sub>STG</sub>	Storage Temperature		-65 to +150		°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit	
V <sub>CCA</sub> , V <sub>CCB</sub>	Positive DC Supply Voltage	0.9	4.5	V	
VI	Bus Input Voltage		GND	4.5	V
V <sub>C</sub>	Control Input	ŌĒ	GND	4.5	V
V <sub>IO</sub>	Bus Output Voltage (Power Down Mode)	B <sub>n</sub>	GND	4.5	V
	(Active Mode)	B <sub>n</sub>	GND	V <sub>CCB</sub>	V
	(Tri-State Mode)	B <sub>n</sub>	GND	4.5	V
T <sub>A</sub>	Operating Temperature Range		-40	+85	°C
Δt / ΔV	Input Transition Rise or Rate V <sub>I</sub> , from 30% to 70% of V <sub>CC</sub> ; V <sub>CC</sub> = 3.3 V $\pm$ 0.3 V	0	10	nS	

# DC ELECTRICAL CHARACTERISTICS

					-40°C to	o +85°C	
Symbol	Parameter	Test Conditions	V <sub>CCA</sub> (V)	V <sub>CCB</sub> (V)	Min	Max	Uni
V <sub>IH</sub>	Input HIGH Voltage		3.6 – 4.5	0.9 - 4.5	2.2	-	V
	(An, $\overline{OE}$ )		2.7 – 3.6	1	2.0	-	
			2.3 – 2.7		1.6	-	
			1.4 – 2.3		0.65 * V <sub>CCA</sub>	-	
			0.9 – 1.4	1	0.9 * V <sub>CCA</sub>	-	
V <sub>IL</sub>	Input LOW Voltage		3.6 – 4.5	0.9 – 4.5	-	0.8	٧
	(An, $\overline{OE}$ )		2.7 – 3.6		-	0.8	
			2.3 – 2.7		_	0.7	
			1.4 – 2.3		_	0.35 * V <sub>CCA</sub>	
			0.9 – 1.4	1	-	0.1 * V <sub>CCA</sub>	
V <sub>OH</sub>	Output HIGH Voltage	I <sub>OH</sub> = -100 μA; V <sub>I</sub> = V <sub>IL</sub>	0.9 – 4.5	0.9 – 4.5	V <sub>CCB</sub> - 0.2	-	٧
		$I_{OH} = -0.5 \text{ mA}; V_I = V_{IL}$	0.9	0.9	0.75 * V <sub>CCB</sub>	_	
		I <sub>OH</sub> = -2 mA; V <sub>I</sub> = V <sub>IL</sub>	1.4	1.4	1.05	_	
		I <sub>OH</sub> = -6 mA; V <sub>I</sub> = V <sub>IL</sub>	1.65	1.65	1.25	_	
			2.3	2.3	2.0	_	
		I <sub>OH</sub> = -12 mA; V <sub>I</sub> = V <sub>IL</sub>	2.3	2.3	1.8	_	
			2.7	2.7	2.2	_	
		I <sub>OH</sub> = -18 mA; V <sub>I</sub> = V <sub>IL</sub>	2.3	2.3	1.7	_	
			3.0	3.0	2.4	_	
		I <sub>OH</sub> = -24 mA; V <sub>I</sub> = V <sub>IL</sub>	3.0	3.0	2.2	_	
V <sub>OL</sub>	Output LOW Voltage	$I_{OL} = 100 \mu A; V_I = V_{IH}$	0.9 – 4.5	0.9 – 4.5	_	0.2	V
		I <sub>OL</sub> = 0.5 mA; V <sub>I</sub> = V <sub>IH</sub>	1.1	1.1	-	0.3	
		I <sub>OL</sub> = 2 mA; V <sub>I</sub> = V <sub>IH</sub>	1.4	1.4	_	0.35	
		I <sub>OL</sub> = 6 mA; V <sub>I</sub> = V <sub>IH</sub>	1.65	1.65	-	0.3	
		I <sub>OL</sub> = 12 mA; V <sub>I</sub> = V <sub>IH</sub>	2.3	2.3	_	0.4	
			2.7	2.7	_	0.4	
		I <sub>OL</sub> = 18 mA; V <sub>I</sub> = V <sub>IH</sub>	2.3	2.3	_	0.6	
			3.0	3.0	_	0.4	
		I <sub>OL</sub> = 24 mA; V <sub>I</sub> = V <sub>IH</sub>	3.0	3.0	_	0.55	
l <sub>l</sub>	Input Leakage Current	$V_I = V_{CCA}$ or GND	0.9 – 4.5	0.9 – 4.5	-1.0	1.0	μA
l <sub>OFF</sub>	Power-Off Leakage Current	<u>OE</u> = 0 V	0 0.9 – 4.5	0.9 – 4.5	-1.0 -1.0	1.0	μΑ
I <sub>CCA</sub>	Quiescent Supply Current	$V_I = V_{CCA}$ or GND; $I_O = 0$ , $V_{CCA} = V_{CCB}$	0.9 – 4.5	0.9 – 4.5	_	2.0	μΑ
I <sub>CCB</sub>	Quiescent Supply Current	$V_I = V_{CCA}$ or GND; $I_O = 0$ , $V_{CCA} = V_{CCB}$	0.9 – 4.5	0.9 – 4.5	-	2.0	μΑ
CCA + ICCB	Quiescent Supply Current	$V_I = V_{CCA}$ or GND; $I_O = 0$ , $V_{CCA} = V_{CCB}$	0.9 – 4.5	0.9 – 4.5	_	4.0	μΑ
$\Delta I_{CCA}$	Increase in $I_{CC}$ per Input Voltage, Other Inputs at $V_{CCA}$ or GND	$V_I = V_{CCA} - 0.6 V;$ $V_I = V_{CCA}$ or GND	4.5 3.6	4.5 3.6	-	10 5.0	μΑ
$\Delta I_{CCB}$	Increase in $I_{CC}$ per Input Voltage, Other Inputs at $V_{CCA}$ or GND	$V_I = V_{CCA} - 0.6 V;$ $V_I = V_{CCA}$ or GND	4.5 3.6	4.5 3.6	-	10 5.0	μΑ
I <sub>OZ</sub>	I/O Tri-State Output Leakage Current	$T_A = 25^{\circ}C, \overline{OE} = 0 \text{ V}$	0.9 – 4.5	0.9 – 4.5	-1.0	1.0	μΑ

TOTAL STATIC POWER CONSUMPTION (I<sub>CCA</sub> + I<sub>CCB</sub>)

					-40°C to	o +85°C					
V <sub>CCB</sub> (V)											
	4.	.5	3.	.3	2.	.8	1.	8	0.	.9	
V <sub>CCA</sub> (V)	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Unit
4.5		2		2		2		2		< 1.5	μА
3.3		2		2		2		2		< 1.5	μА
2.8		< 2		< 1		< 1		< 0.5		< 0.5	μА
1.8		< 1		< 1		< 0.5		< 0.5		< 0.5	μА
0.9		< 0.5		< 0.5		< 0.5		< 0.5		< 0.5	μΑ

 $NOTE: Connect ground before applying supply voltage \ V_{CCA} \ or \ V_{CCB}. \ This device is designed with the feature that the power-up sequence$ of  $V_{CCA}$  and  $V_{CCB}$  will not damage the IC.

### **AC ELECTRICAL CHARACTERISTICS**

							-40°C to	o +85°C					
							V <sub>CCI</sub>	<sub>B</sub> (V)					
			4	.5	3.	.3	2.	.8	1.	.8	1.	2	
Symbol	Parameter	V <sub>CCA</sub> (V)	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Unit
t <sub>PLH</sub> ,	Propagation	4.5		1.6		1.8		2.0		2.1		2.3	nS
t <sub>PHL</sub> (Note 1)	Delay,	3.3		1.7		1.9		2.1		2.3		2.6	
(Note 1)	A <sub>n</sub> to B <sub>n</sub>	2.8		1.9		2.1		2.3		2.5		2.8	
		1.8		2.1		2.4		2.5		2.7		3.0	
		1.2		2.4		2.7		2.8		3.0		3.3	
t <sub>PZH</sub> ,	Output	4.5		2.6		3.8		4.0		4.1		4.3	nS
t <sub>PZL</sub>	Enable,	3.3		3.7		3.9		4.1		4.3		4.6	
(Note 1)	OE to B <sub>n</sub>	2.5		3.9		4.1		4.3		4.5		4.8	
		1.8		4.1		4.4		4.5		4.7		5.0	
		1.2		4.4		4.7		4.8		5.0		5.3	
t <sub>PHZ</sub> ,	Output	4.5		2.6		3.8		4.0		4.1		4.3	nS
t <sub>PLZ</sub>	Disable,	3.3		3.7		3.9		4.1		4.3		4.6	
(Note 1)	OE to B <sub>n</sub>	2.5		3.9		4.1		4.3		4.5		4.8	
		1.8		4.1		4.4		4.5		4.7		5.0	
		1.2		4.4		4.7		4.8		5.0		5.3	
t <sub>OSHL</sub> ,	Output to	4.5		0.15		0.15		0.15		0.15		0.15	nS
toslh	Output Skew,	3.3		0.15		0.15		0.15		0.15		0.15	
(Note 1)	Time	2.5		0.15		0.15		0.15		0.15		0.15	
		1.8		0.15		0.15		0.15		0.15		0.15	
		1.2		0.15		0.15		0.15		0.15		0.15	

<sup>1.</sup> Propagation delays defined per Figure 2.

#### **CAPACITANCE**

Symbol	Parameter	Test Conditions	Typ (Note 2)	Unit
C <sub>IN</sub>	Control Pin Input Capacitance	$V_{CCA} = V_{CCB} = 3.3 \text{ V}, V_I = 0 \text{ V or } V_{CCA/B}$	3.5	pF
C <sub>I/O</sub>	I/O Pin Input Capacitance	$V_{CCA} = V_{CCB} = 3.3 \text{ V}, V_I = 0 \text{ V or } V_{CCA/B}$	5.0	pF
C <sub>PD</sub>	Power Dissipation Capacitance	$V_{CCA} = V_{CCB} = 3.3 \text{ V}, V_{I} = 0 \text{ V or } V_{CCA}, f = 10 \text{ MHz}$	20	pF

Typical values are at T<sub>A</sub> = +25°C.
 C<sub>PD</sub> is defined as the value of the IC's equivalent capacitance from which the operating current can be calculated from: I<sub>CC(operating)</sub> ≅ C<sub>PD</sub> x V<sub>CC</sub> x f<sub>IN</sub> x N<sub>SW</sub> where I<sub>CC</sub> = I<sub>CCA</sub> + I<sub>CCB</sub> and N<sub>SW</sub> = total number of outputs switching.

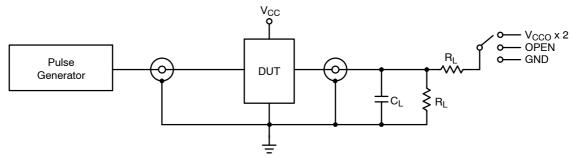


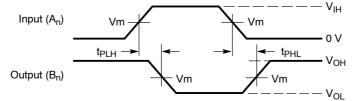
Figure 2. AC (Propagation Delay) Test Circuit

Test	Switch
t <sub>PLH</sub> , t <sub>PHL</sub>	OPEN
t <sub>PLZ</sub> , t <sub>PZL</sub>	V <sub>CCO</sub> x 2
t <sub>PHZ</sub> , t <sub>PZH</sub>	GND

 $C_L$  = 15 pF or equivalent (includes probe and jig capacitance)

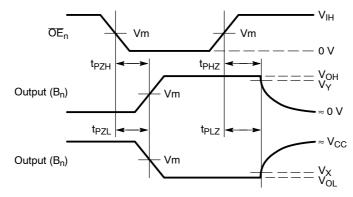
 $R_L = 2 k\Omega$  or equivalent

 $Z_{OUT}$  of pulse generator = 50  $\Omega$ 



### Waveform 1 - Propagation Delays

 $t_R = t_F = 2.0 \text{ ns}, 10\% \text{ to } 90\%; f = 1 \text{ MHz}; t_W = 500 \text{ ns}$ 



### Waveform 2 - Output Enable and Disable Times

 $t_{R}$  =  $t_{F}$  = 2.0 ns, 10% to 90%; f = 1 MHz;  $t_{W}$  = 500 ns

Figure 3. AC (Propagation Delay) Test Circuit Waveforms

	V <sub>CC</sub>							
Symbol	3.0 V – 4.5 V	2.3 V – 2.7 V	1.65 V – 1.95 V	1.4 V – 1.6 V	0.9 V – 1.3 V			
V <sub>mA</sub>	V <sub>CCA</sub> /2							
V <sub>mB</sub>	V <sub>CCB</sub> /2							
V <sub>X</sub>	V <sub>OL</sub> x 0.1							
V <sub>Y</sub>	V <sub>OH</sub> x 0.9							

### UQFN12 1.7x2.0, 0.4P CASE 523AE-01 **ISSUE A**



**DATE 11 JUN 2007** 



PIN 1 REFERENCE

2X |

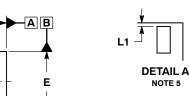
12X 🗀

0.10 C

0.10 C

0.05

0.05



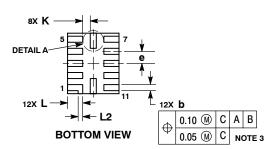


CONSTRUCTION

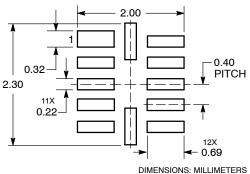
С C **A1** SEATING PLANE SIDE VIEW

DETAIL B

**TOP VIEW** 



### **MOUNTING FOOTPRINT SOLDERMASK DEFINED**



#### NOTES:

- DIMENSIONING AND TOLERANCING PER ASME
- Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS
- DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM
- FROM TERMINAL TIP.

  MOLD FLASH ALLOWED ON TERMINALS

  ALONG EDGE OF PACKAGE. FLASH 0.03

  MAX ON BOTTOM SURFACE OF
- TERMINALS.
  DETAIL A SHOWS OPTIONAL
  CONSTRUCTION FOR TERMINALS.

	MILLIMETERS							
DIM	MIN	MAX						
Α	0.45	0.55						
A1	0.00	0.05						
A3	0.127 REF							
b	0.15	0.25						
D	1.70	BSC						
Е	2.00	BSC						
е	0.40	BSC						
K	0.20							
L	0.45	0.55						
L1	0.00	0.03						
12	0.15	REF						

### **GENERIC MARKING DIAGRAM\***



XX = Specific Device Code

= Date Code

= Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

DOCUMENT NUMBER:	98AON23418D	Electronic versions are uncontrolled except when accessed directly from Printed versions are uncontrolled except when stamped "CONTROLLED	
DESCRIPTION:	UQFN12 1.7 X 2.0, 0.4P		PAGE 1 OF 1

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